

SOT1343-1

plastic thin fine-pitch ball grid array package; 484 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA484
Package type industry code	TFBGA484
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-11-2012

Table 1. Package summary

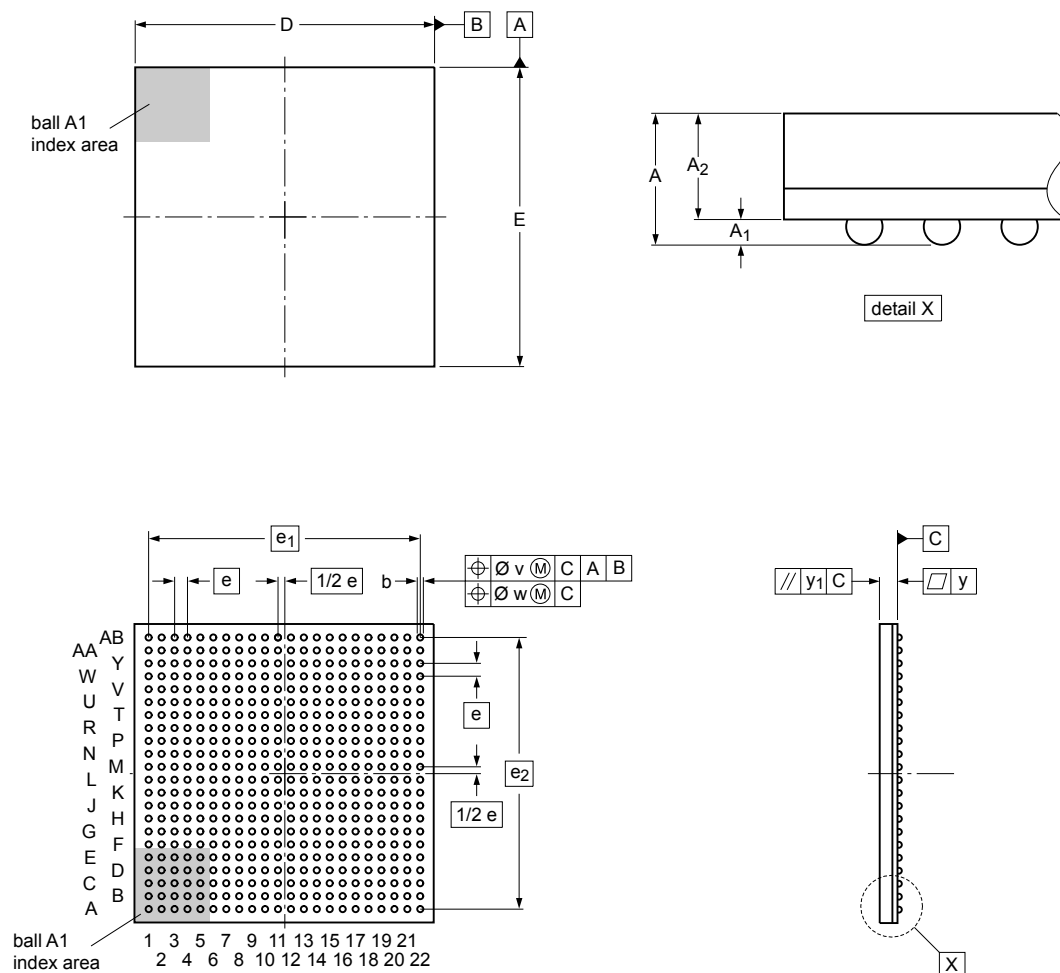
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.9	-	15	15.1	mm
E	package width		14.9	-	15	15.1	mm
A	seated height		[tbd]	-	[tbd]	1.2	mm
A ₂	package height		0.84	-	0.89	0.94	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	484	-	



2. Package outline

TFBGA484: plastic thin fine-pitch ball grid array package; 484 balls

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A horizontal scale bar with a vertical tick mark at the left end labeled '0' and a vertical tick mark at the right end labeled '10 mm'. There are nine evenly spaced vertical tick marks between the ends, creating ten equal segments. The word 'scale' is centered below the bar.

Dimensions (mm are the original dimensions)

Unit		A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	max	1.2	0.26	0.94	0.35	15.1	15.1							
	nom		0.21	0.89	0.30	15.0	15.0	0.65	13.65	13.65	0.15	0.08	0.10	0.2
	min		0.16	0.84	0.25	14.9	14.9							

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Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
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Fig. 1. Package outline TFBGA484 (SOT1343-1)

3. Legal information

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